

ABSTRACT

A switch device and method for manufacturing the switch device in which substrates are provided collectively having defined therein a liquid metal switch and a sub-channel connected to the liquid metal switch. A cavity filled with sacrificial material is formed in a first one of the substrates. A heater element is formed at least in part over the sacrificial material and conductive vias are formed extending through one of the substrates to the heater element. The sacrificial material is removed and the substrates are joined with an adhesive seal.